

Modeling and Analysis of VLSI Interconnects



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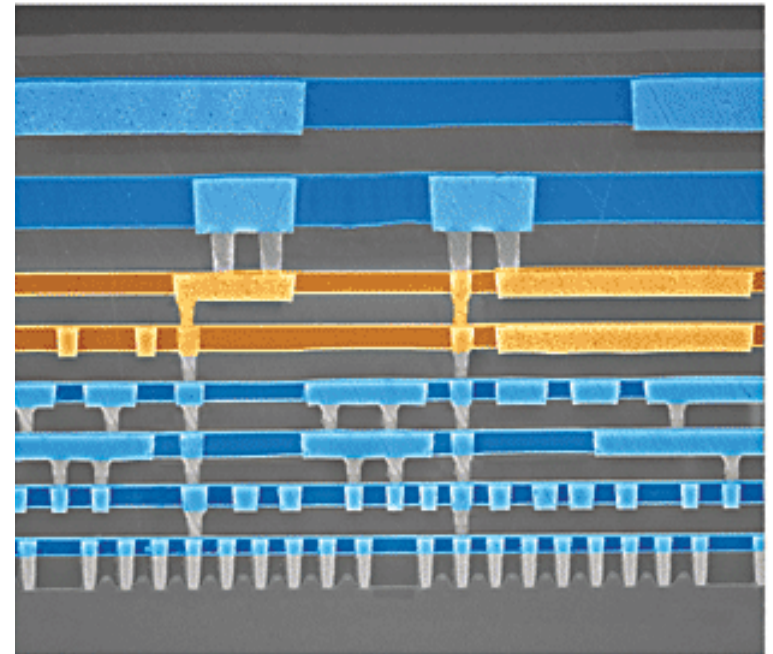
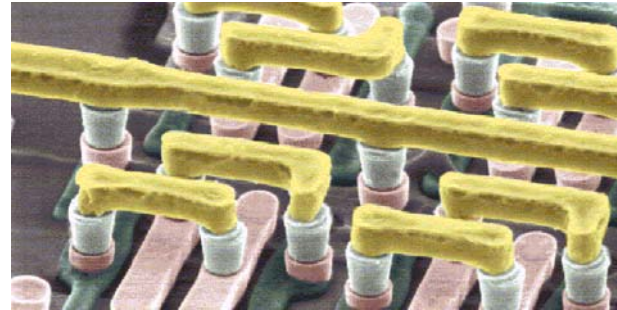
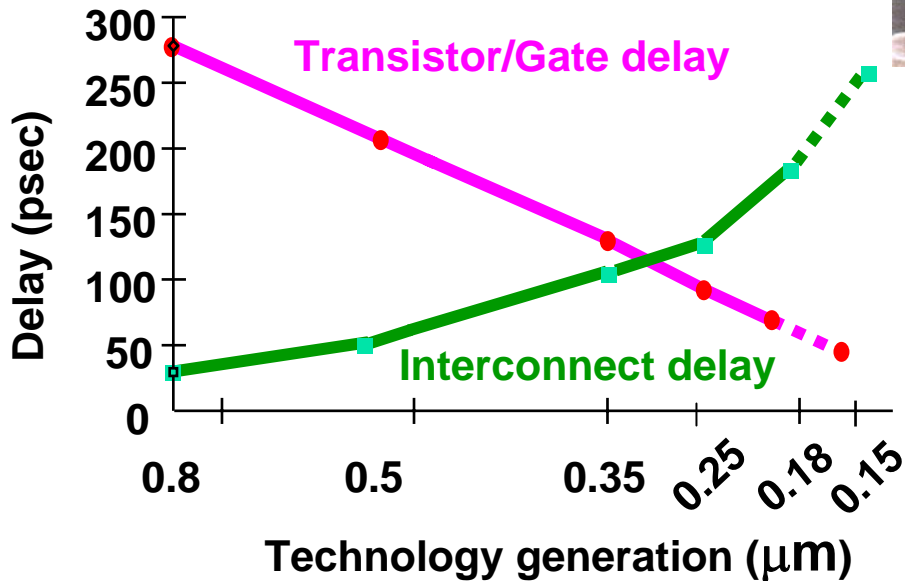
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Outline

- Introduction
- Capacitance extraction
- Inductance modeling
- Conclusion

Interconnects do not scale well



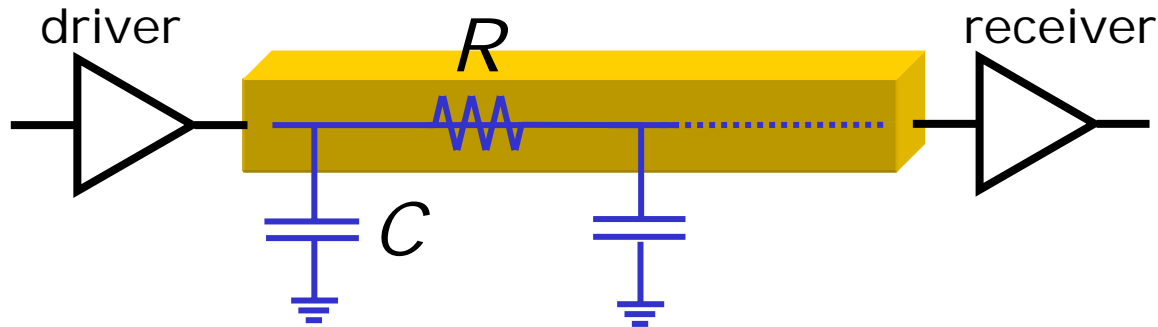
[Gordon Moore, Chairman Emeritus, Intel Corp.]

International Technology Roadmap for Semiconductor

Year	2005	2006	2007	2008	2009	2010	2011	2012	2013
Technology (nm)	80	70	65	57	50	45	40	36	32
Max # wiring levels	15	15	15	16	16	16	16	16	17
M1 RC (ps)	440	612	767	1044	1388	1782	2392	2857	3451
M1 resistivity ($\mu\Omega\text{-cm}$)	3.15	3.29	3.47	3.67	3.90	4.08	4.30	4.63	4.83
M1 capacitance (pF/cm)	2.0- 2.2	2.0- 2.2	1.8- 2.0	1.9- 2.1	1.8- 2.0	1.8- 2.0	1.8- 2.0	1.6- 1.8	1.6- 1.8
Global wire RC (ps)	111	165	209	316	410	523	687	787	977
Global wire resistivity ($\mu\Omega\text{-cm}$)	2.53	2.62	2.73	2.87	3.00	3.10	3.22	3.39	3.52
Global wire capacitance (pF/cm)	2.1- 2.3	2.1- 2.3	1.8- 2.0	1.8- 2.0	1.7- 1.9	1.7- 1.9	1.7- 1.9	1.5- 1.7	1.5- 1.7

[ITRS'05 and '06, <http://www.itrs.net>)]

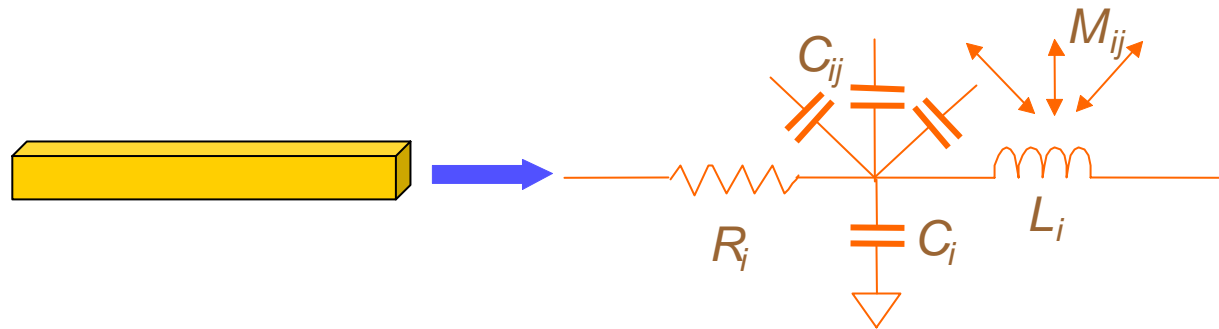
Interconnect Modeling



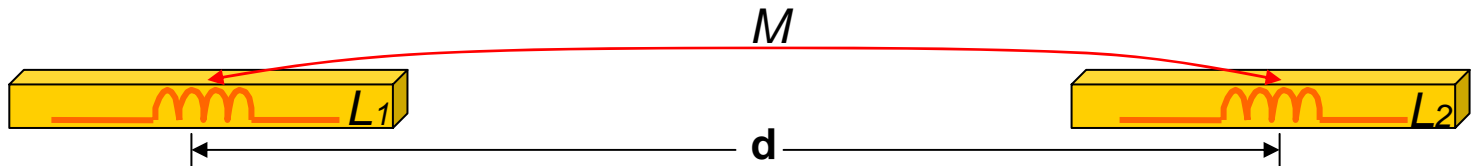
- Capacitance only model
- RC model now widely used
- How about inductance?
 - Ignored at low frequency ($\omega L \ll R$)
- Inductance can no longer be ignored
 - Increasing operation frequency
 - Lower wire resistance

Partial Element Equivalent Circuit

- PEEC Model [A. Ruehli, IBM Journal of R&D, 1972]



- Retardation



$$V_2(t) = L_2 \frac{di_2(t)}{dt} + M \frac{di_1(t - d/v)}{dt}$$

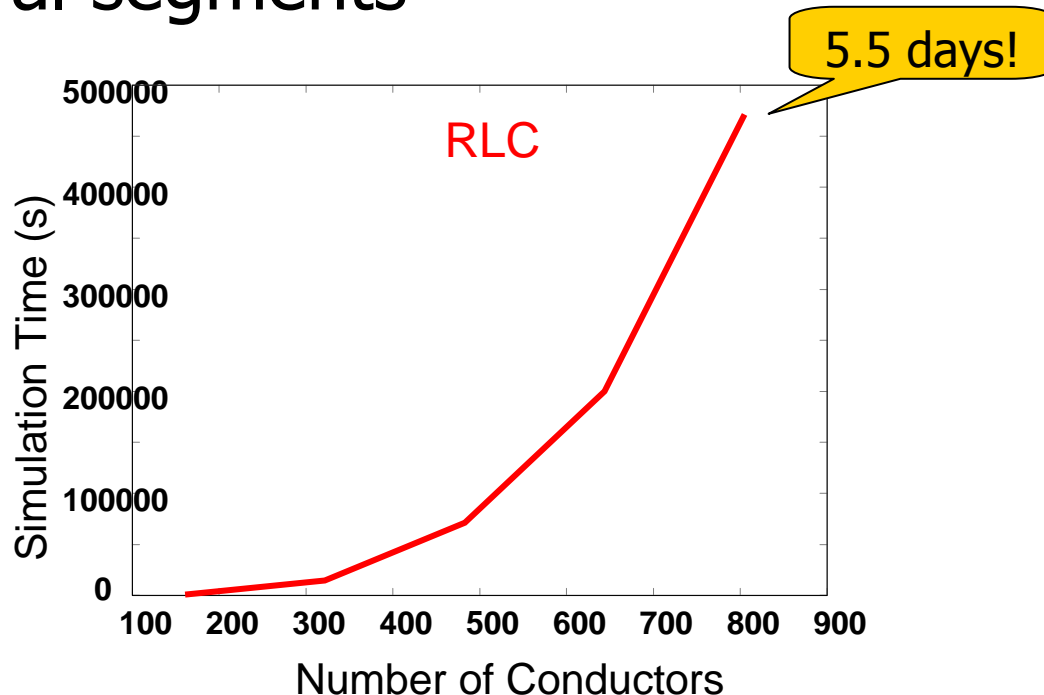
Full-wave PEEC

$$V_2(t) = L_2 \frac{di_2(t)}{dt} + M \frac{di_1(t)}{dt}$$

Quasi-static assumption

Interconnect Modeling Challenge

- Extraction of RLC parameters and simulation of interconnects are large scale problems
- Long interconnects have to be divided into several segments



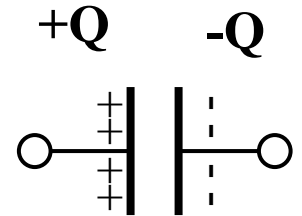


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What is capacitance?

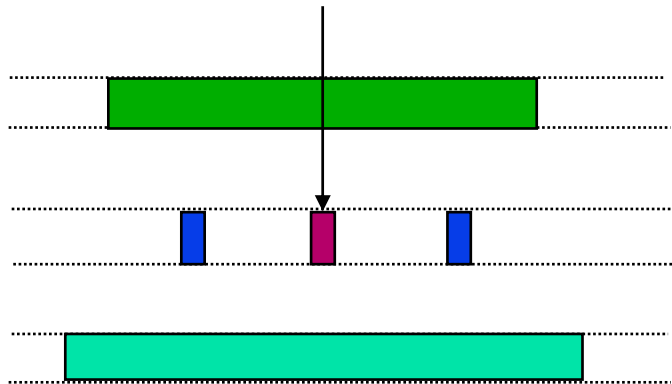
- Simplest model: parallel-plate capacitor
- Two parallel plates and homogeneous dielectric between them
- The capacitance is $C = \varepsilon \frac{A}{d}$
 - ε : permittivity of dielectric
 - A : area of plate
 - d : distance between plates
- The capacitance is the capacity to store charge
 - Total charge at each plate is $Q = CV$
 - One is positive, the other is negative



On-chip interconnects as capacitors

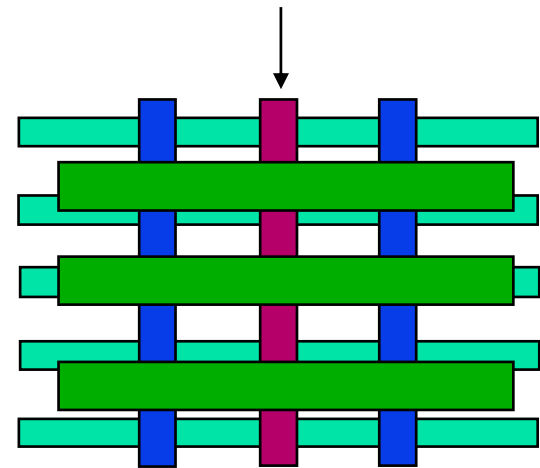
- Conductors: metal wire, via, polysilicon, substrate
- Dielectrics: SiO_2 , ...

victim



cross-section

victim



top-view

Multiconductor systems

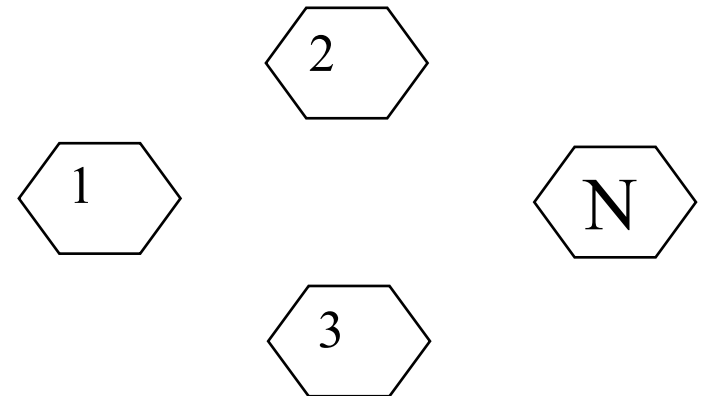
- The presence of charge on any one of the conductors affects the potential of all the others
- Linear proportionality between potential and charge

$$V_1 = p_{11}Q_1 + p_{12}Q_2 + \cdots + p_{1N}Q_N$$

$$V_2 = p_{21}Q_1 + p_{22}Q_2 + \cdots + p_{2N}Q_N$$

⋮

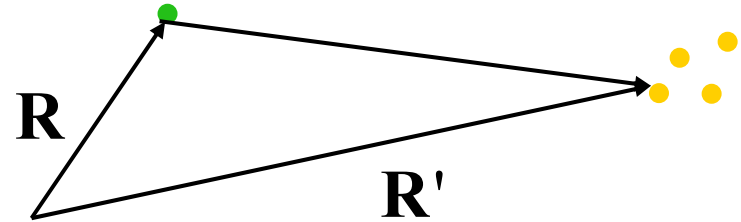
$$V_N = p_{N1}Q_1 + p_{N2}Q_2 + \cdots + p_{NN}Q_N$$



Electric potential

- Electric potential at \mathbf{R} due to n charged bodies q_1, \dots, q_n , located at $\mathbf{R}'_1, \dots, \mathbf{R}'_n$

$$V = \frac{1}{4\pi\epsilon} \sum_{k=1}^n \frac{q_k}{|\mathbf{R} - \mathbf{R}'_k|}$$



- Electric potential due to a continuous distribution of charge confined in a given region:

$$V = \frac{1}{4\pi\epsilon} \int_{V'} \frac{\rho}{R} dv'$$

volume

$$V = \frac{1}{4\pi\epsilon} \int_{S'} \frac{\rho_s}{R} ds'$$

surface

$$V = \frac{1}{4\pi\epsilon} \int_{L'} \frac{\rho_l}{R} dl'$$

line

(Partial) Capacitance matrix

- Inverting the system of linear equations

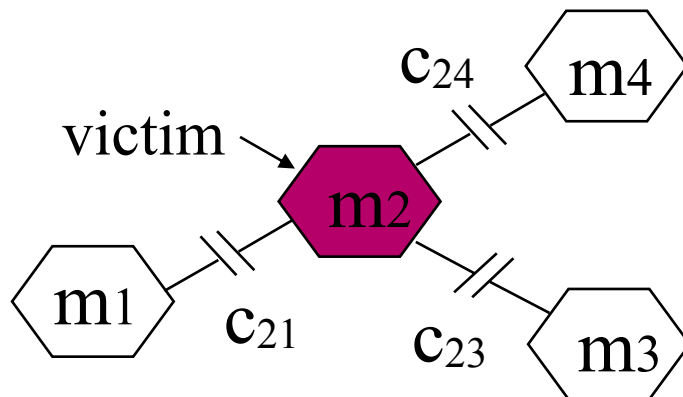
$$\begin{array}{l} V_1 = p_{11}Q_1 + p_{12}Q_2 + \cdots + p_{1N}Q_N \\ V_2 = p_{21}Q_1 + p_{22}Q_2 + \cdots + p_{2N}Q_N \\ \vdots \\ V_N = p_{N1}Q_1 + p_{N2}Q_2 + \cdots + p_{NN}Q_N \end{array} \quad \rightarrow \quad \begin{array}{l} Q_1 = c_{11}V_1 + c_{12}V_2 + \cdots + c_{1N}V_N \\ Q_2 = c_{21}V_1 + c_{22}V_2 + \cdots + c_{2N}V_N \\ \vdots \\ Q_N = c_{N1}V_1 + c_{N2}V_2 + \cdots + c_{NN}V_N \end{array}$$

- The c_{ii} 's are coefficients of capacitance (self capacitance)
- The c_{ij} 's ($i \neq j$) are coefficients of induction (coupling capacitance)

$O(n^3)$ for Gaussian elimination, $O(n^{2.807})$ [Strassen 1969],
 $O(n^{2.376})$ [Coppersmith and Winograd 1990]

Framework for numerical method

1. Assume voltage $[0, 0, \dots, 1, \dots, 0]$, i.e., only conductor i has unit voltage
2. Compute charge q_j for every conductor j
3. Obtain mutual cap $c_{ij} = q_j$ and total cap $c_{ii} = q_i$
4. Iterate through steps 1-3 using different voltage assignments



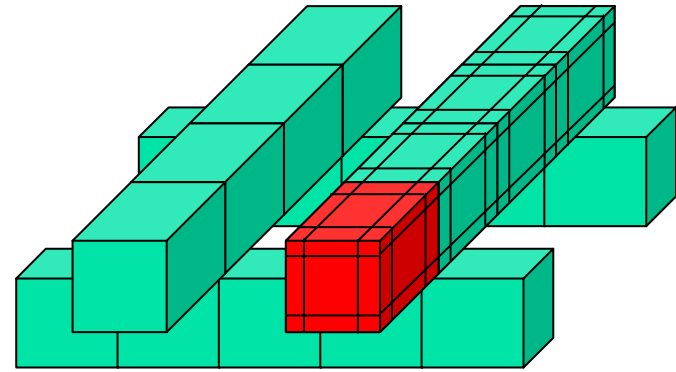
$$V = \begin{matrix} 0 & 1 & 0 & 0 \end{matrix}$$



$$C = \begin{matrix} 0 & C_{12} & 0 & 0 \\ C_{21} & C_{22} & C_{23} & C_{24} \\ 0 & C_{32} & 0 & 0 \\ 0 & C_{42} & 0 & 0 \end{matrix}$$

Integral equation approach

- Discretize the surfaces of m conductors into a total of n panels
- Write down potential coefficient matrix and linear system $Pq = v$



$$P_{ij} = \frac{1}{\text{area}(A_i)} \times \int_{x_i \in A_i} \frac{1}{\text{area}(A_j)} \int_{x_j \in A_j} \frac{1}{4\pi\epsilon_0 \|x_i - x_j\|} da_j da_i$$

- Set $v_k = 1$ if panel k is on the j -th conductor, and $v_k = 0$ otherwise
- Solve for panel charge q and sum all the panel charge on the i -th conductor $C_{ij} = \sum_{k \in \text{conductor } i} q_k$

Numerical solution by method of conjugate gradient

- Initial guess $\mathbf{q}_{(0)} = \mathbf{0}$
- Residual $\mathbf{r}_{(i)} = \mathbf{v} - \mathbf{P}\mathbf{q}_{(i)}$
- Initialize search direction and residual $\mathbf{d}_{(0)} = \mathbf{r}_{(0)} = \mathbf{v}$
- Iterate

$$\alpha_{(i)} = \frac{\mathbf{r}_{(i)}^T \mathbf{r}_{(i)}}{\mathbf{d}_{(i)}^T \mathbf{P} \mathbf{d}_{(i)}}$$

$$\mathbf{q}_{(i+1)} = \mathbf{q}_{(i)} + \alpha_{(i)} \mathbf{d}_{(i)}$$

$$\mathbf{r}_{(i+1)} = \mathbf{r}_{(i)} - \alpha_{(i)} \mathbf{P} \mathbf{d}_{(i)}$$

$$\beta_{(i+1)} = \frac{\mathbf{r}_{(i+1)}^T \mathbf{r}_{(i+1)}}{\mathbf{r}_{(i)}^T \mathbf{r}_{(i)}}$$

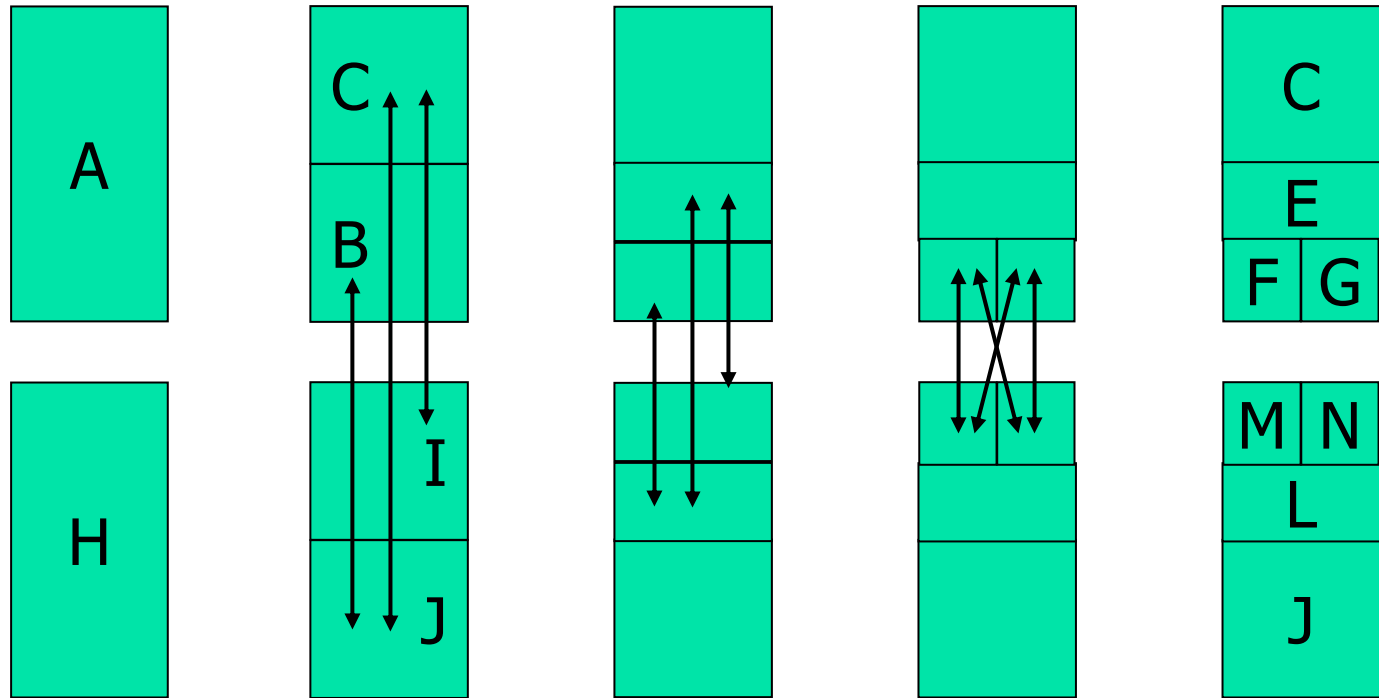
$$\mathbf{d}_{(i+1)} = \mathbf{r}_{(i+1)} + \beta_{(i+1)} \mathbf{d}_{(i)}$$



Fast multi-pole method (FMM)

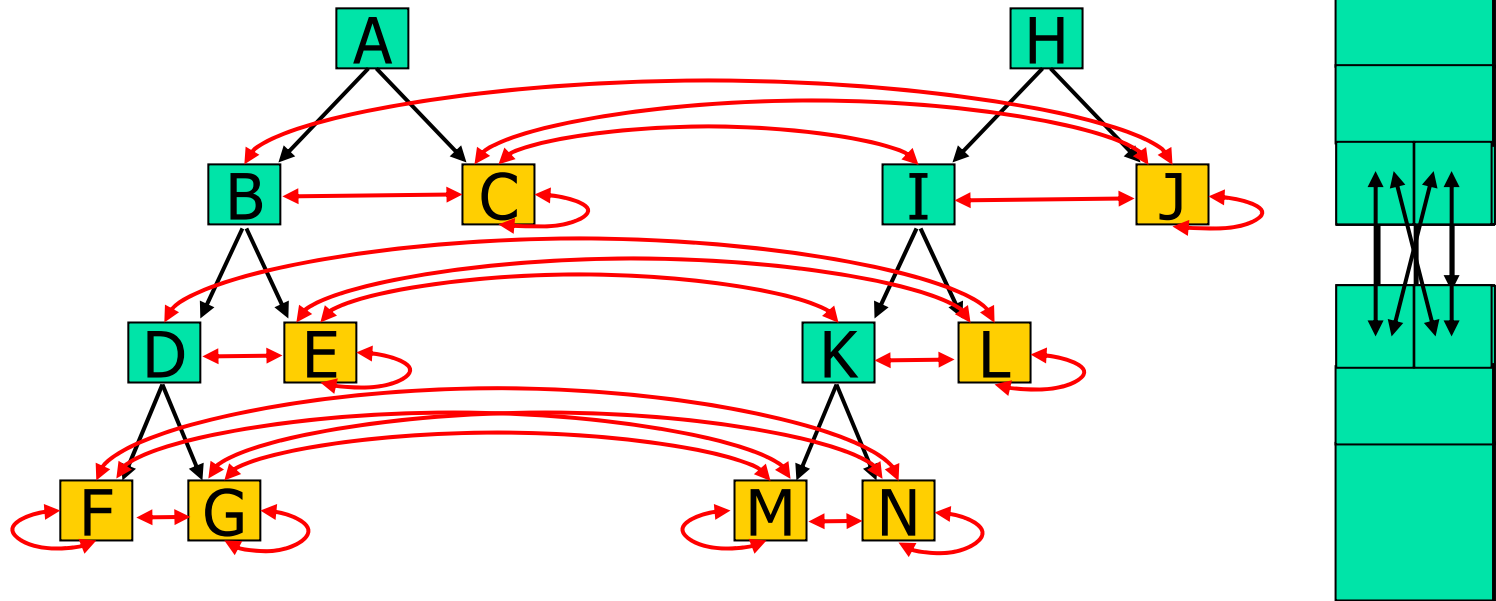
- Bottleneck is in the computation of the potential on all panels, i.e., matrix-vector multiply $Pd_{(i)}$
- Known as the n-body problem, can be solved in $O(n)$ without loss in accuracy (machine precision) using FMM [Greengard-Rohklin] and [Appel]
- Basic idea: Potential due to a cluster of particles at some distance can be approximated with a single term
- FastCap from MIT [Nabors-White] and hierarchical capacitance extraction from Texas-A&M [Shi et al] used different forms of FMM in the iterative solvers

Hierarchical partitioning



- $R_i =$ longest dimension of panel i
- If $P_\varepsilon < P_{ij} \times R_i (\approx R_i / r_{ij})$, subdivide the panel
- Record potential coefficient between two panels otherwise

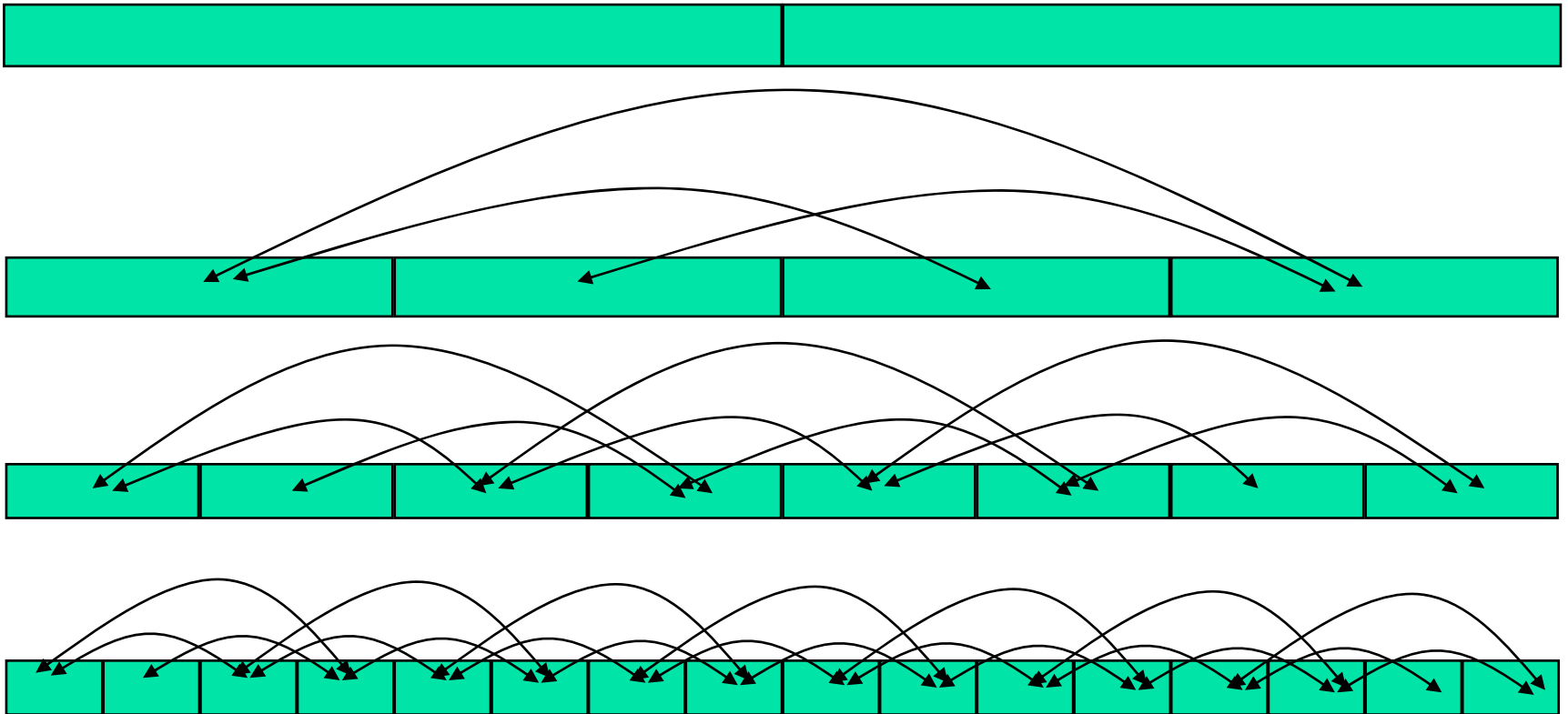
Binary trees with cross links



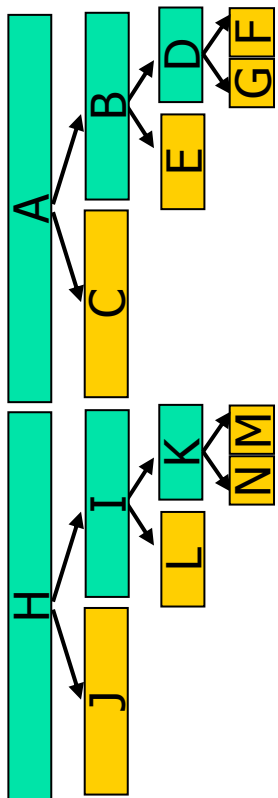
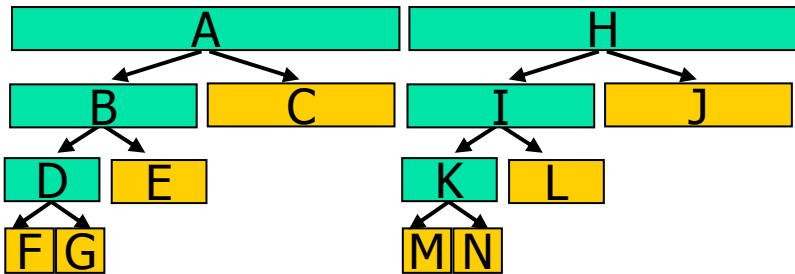
- Cross links record the potential coefficient between two panels

$O(1)$ number of cross links per node

- Two panels interact directly only if $r_{ij} > R_i \times P_\varepsilon$, i.e., there are k panels between them
- Otherwise, parent nodes would have interacted



Matrix-vector multiply: $Pq = v$



1	2	4	15	16	19	22
	3		17	18		
		5	20	21		
			6			
			7	23		24
			8	9	11	13
				10		
					12	
						14

C.potential

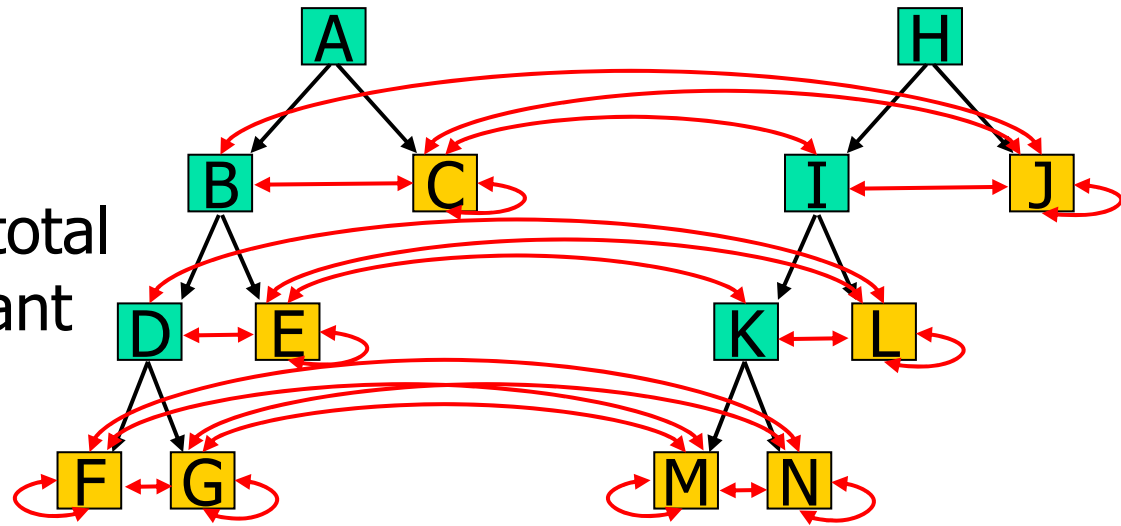
$$\begin{aligned}
 &= P_{CB}F.\text{charge} + \\
 &P_{CB}G.\text{charge} + \\
 &P_{CE}E.\text{charge} + \\
 &P_{CI}M.\text{charge} + \\
 &P_{CI}N.\text{charge} + \\
 &P_{CI}L.\text{charge} + \\
 &P_{CJ}J.\text{charge}
 \end{aligned}$$

$$\begin{aligned}
 &= P_{CB}B.\text{charge} + \\
 &P_{CC}C.\text{charge} + \\
 &P_{CI}I.\text{charge} + \\
 &P_{CJ}J.\text{charge}
 \end{aligned}$$

$O(n)$ matrix-vector multiply

- Collect charge

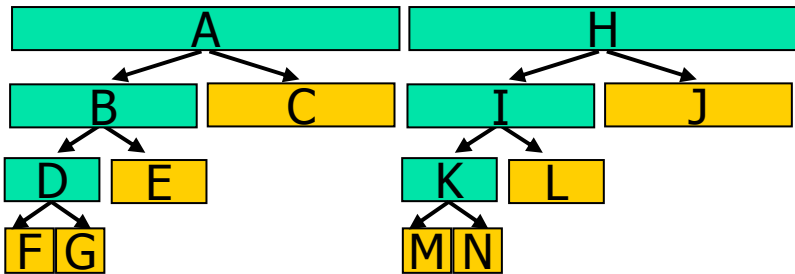
- Charge at node = total charge at descendant leaf nodes ($d_{(i)}$)



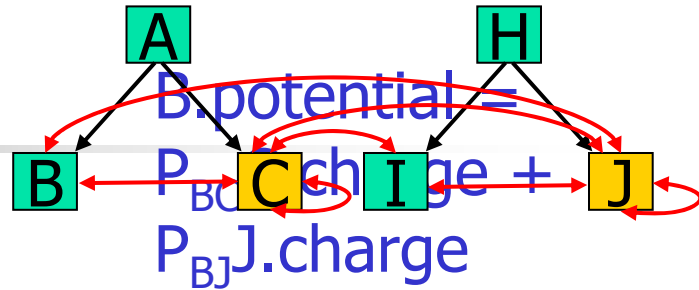
- Bottom-up traversal of trees, propagate charge at leaf nodes upwards

- $D.\text{charge} = F.\text{charge} + G.\text{charge} = d_{(i),F} + d_{(i),G}$
- $B.\text{charge} = D.\text{charge} + E.\text{charge} = D.\text{charge} + d_{(i),E}$
- $A.\text{charge} = B.\text{charge} + C.\text{charge} = B.\text{charge} + d_{(i),C}$

Matrix-vector multiply



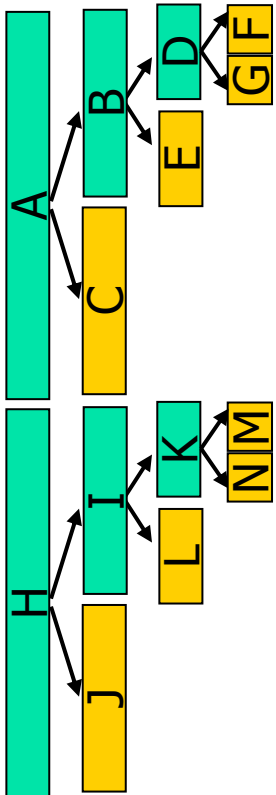
1	2	4	15	16	19	
	3		17	18		22
		5		20	21	
			7		23	24
				8	9	
					10	11
						12
						13
						14



E.potential

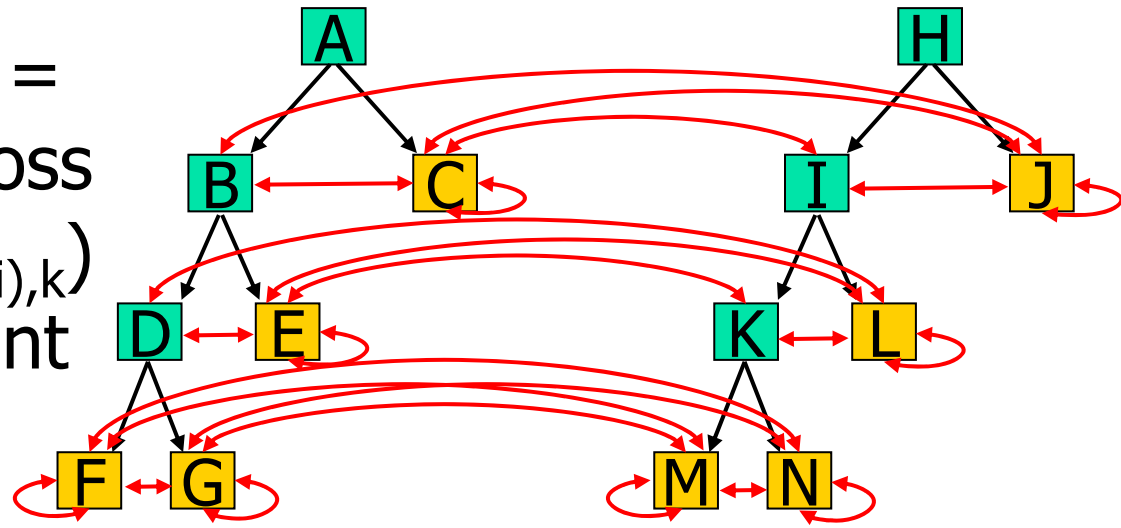
$$\begin{aligned}
 = & P_{ED} D.charge + \\
 & P_{EE} E.charge + \\
 & P_{BC} C.charge + \\
 & P_{EK} K.charge + \\
 & P_{EL} L.charge + \\
 & P_{BJ} J.charge
 \end{aligned}$$

$$\begin{aligned}
 = & \text{B.potential} + \\
 & P_{ED} D.charge + \\
 & P_{EE} E.charge + \\
 & P_{EK} K.charge + \\
 & P_{EL} L.charge
 \end{aligned}$$



$O(n)$ matrix-vector multiply

- Potential at node j = potential due to cross links at node ($P_{jk}d_{(i),k}$) + potential of parent



- Top-down traversal of trees, propagate potential at root nodes downwards
 - A.potential = 0
 - B.potential = A.potential + P_{BC} C.charge + P_{BJ} J.charge
 - D.potential = B.potential + P_{DE} E.charge + P_{DL} L.charge
 - F.potential = D.potential + $P_{F\{FGMN\}}$ {FGMN}.charge



Summary

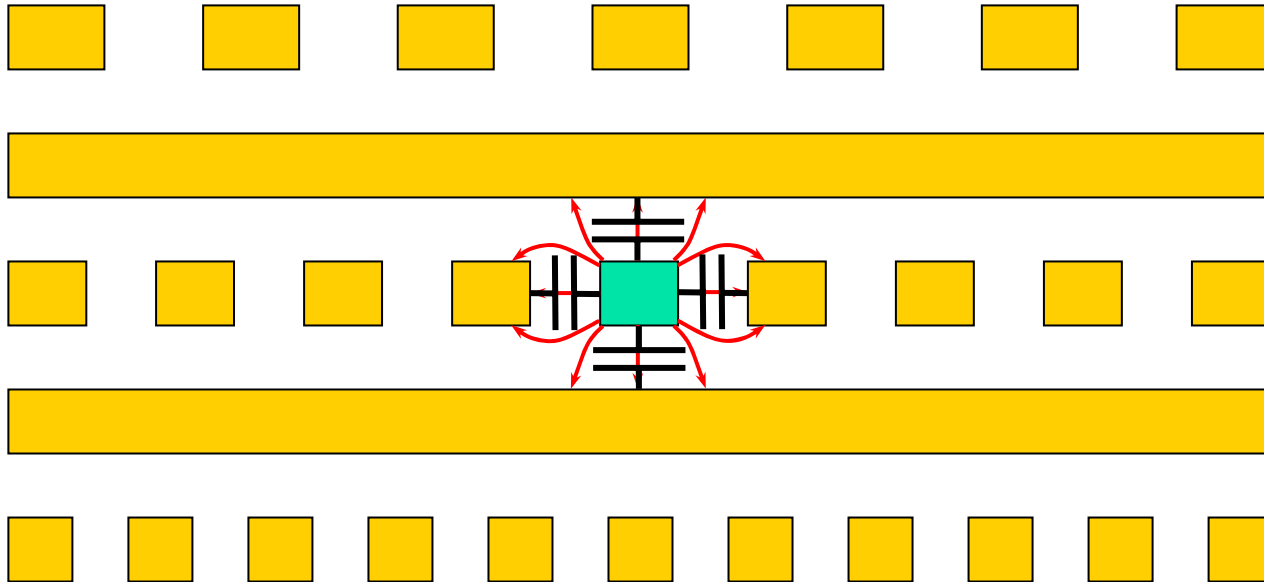
- For n panels, $O(n)$ fast matrix-vector multiply based on FMM
- Tree structures with cross links to facilitate $O(n)$ matrix-vector multiply by bottom-up and top-down tree traversals
- $O(kn)$ time complexity for each solve of conductor charge, k being the number of iterations
- Assume m conductors with n panels, overall complexity is $O(kmn)$



Outline

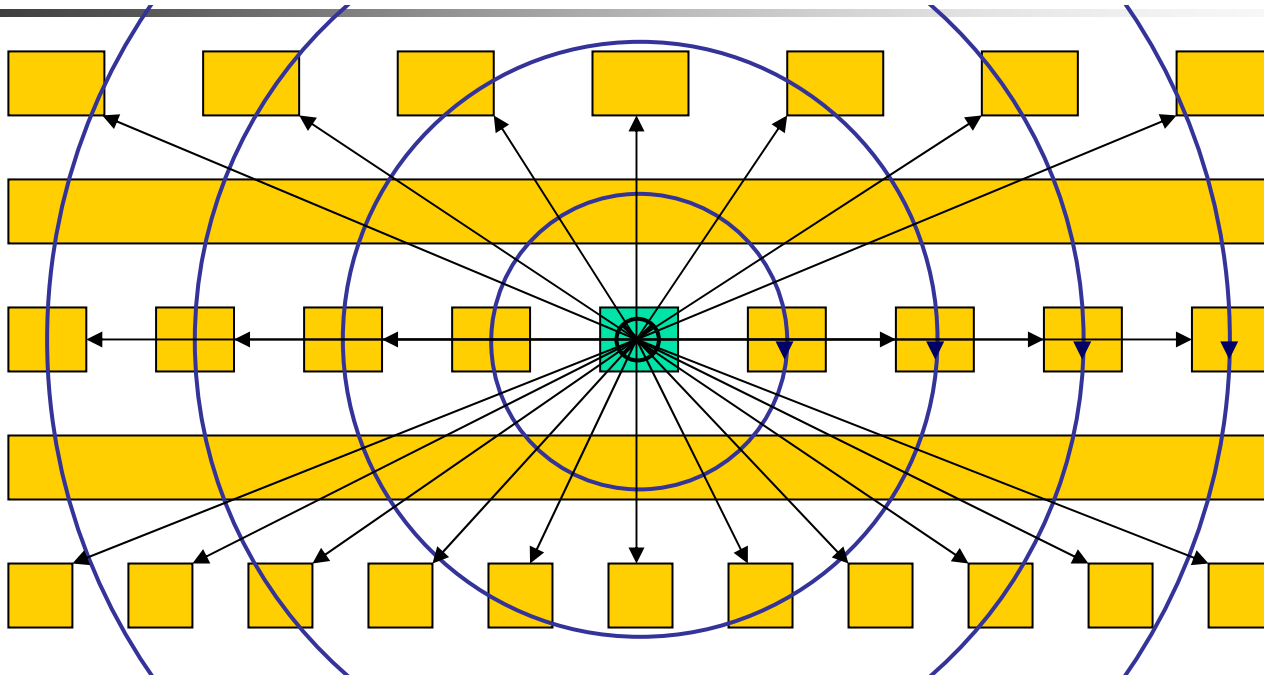
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Capacitive Coupling Property



- Coupling capacitance
 - Limited to adjacent neighbors
 - Limited to adjacent layers

Inductive Coupling Property

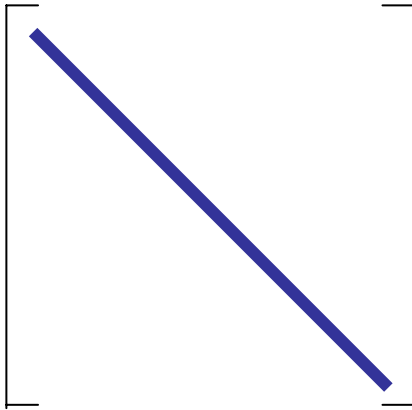


■ Mutual Inductance

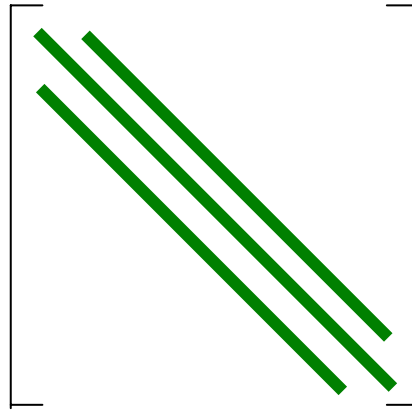
- Not limited to adjacent wires
- Not limited to adjacent layers
- Exists among all parallel wires



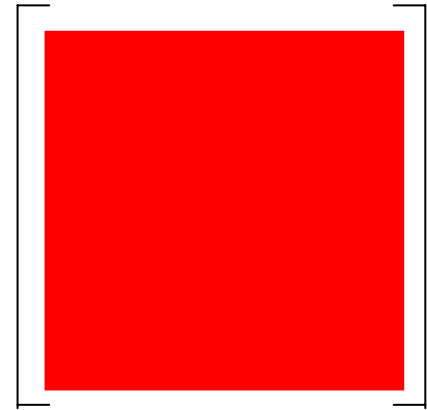
RLC Matrices



R is diagonal



C is tridiagonal



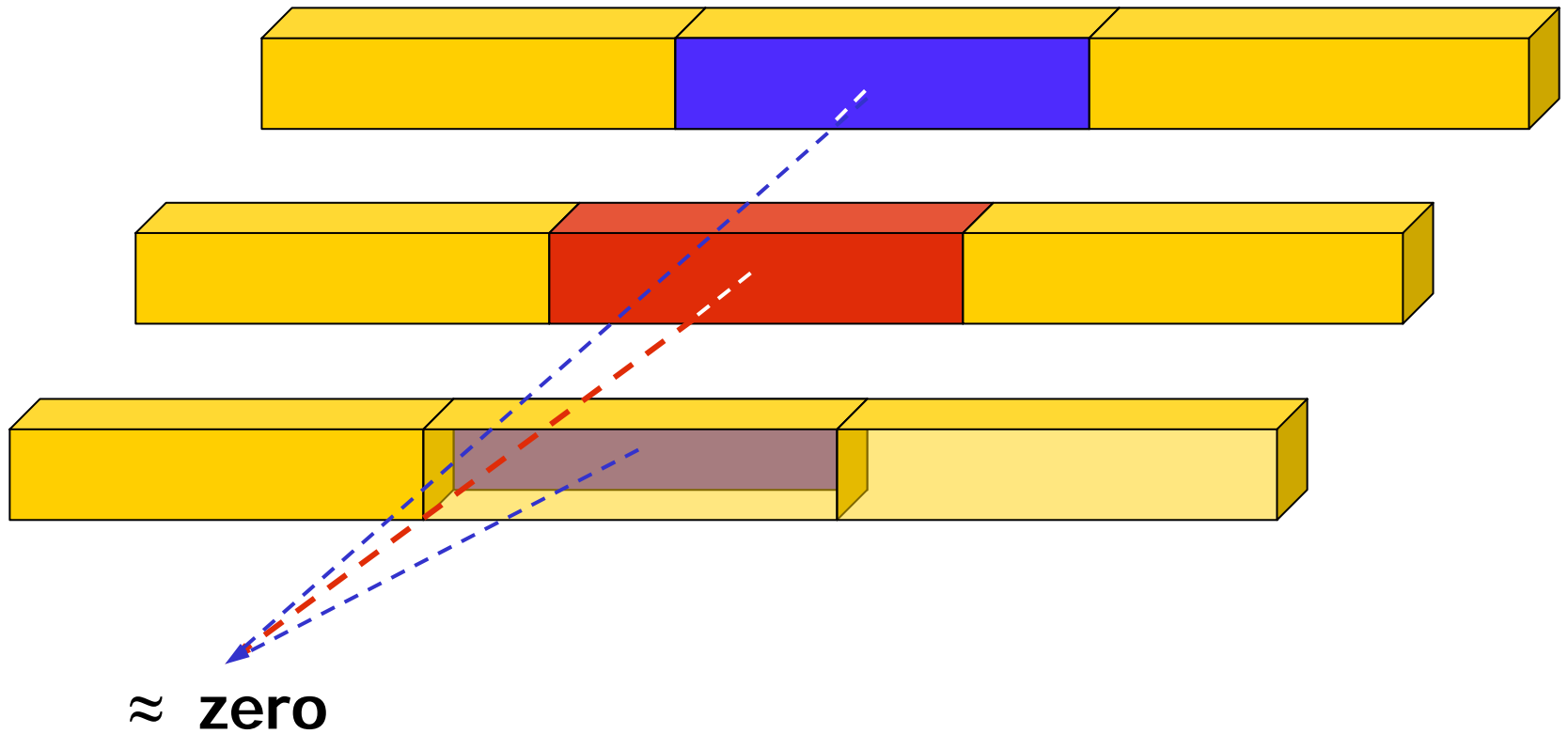
L is FULL



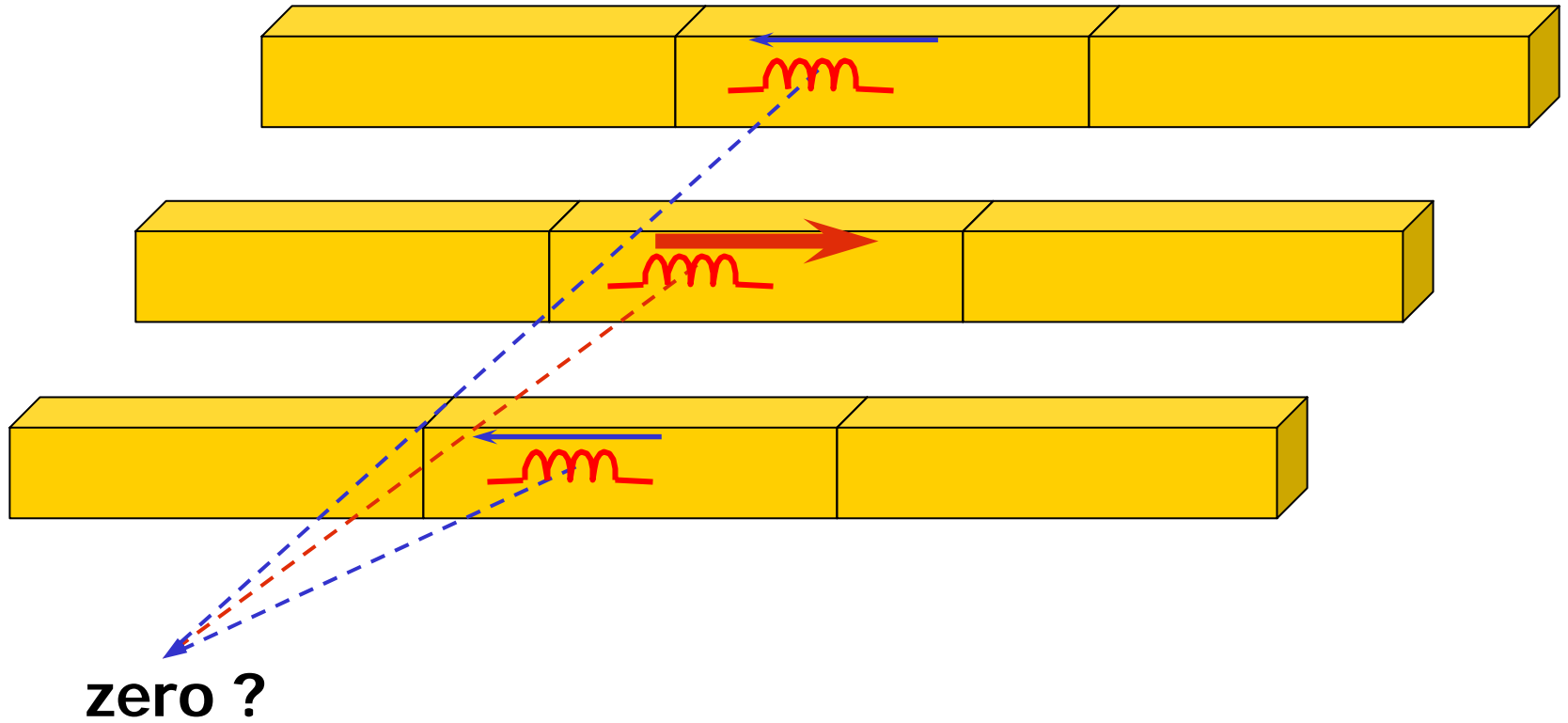
Questions

- Is there sparsity pattern related with L ?
- How can we exploit such sparsity pattern in the simulation of RLC on-chip interconnects?

Locality of Capacitive Coupling



Is Inductive Coupling Localized?





Sparsity Resident in L^{-1}

$$L = 10^{-11} \times$$

$$\begin{bmatrix} 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 & 5.13 \\ 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 \\ 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 \\ 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 \\ 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 \\ 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 \\ 5.13 & 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 \end{bmatrix}$$

$$L^{-1} = 10^{10} \times$$

$$\begin{bmatrix} 2.53 & -1.67 & -0.12 & -0.12 & -0.08 & -0.05 & -0.11 \\ -1.67 & 3.63 & -1.60 & -0.04 & -0.07 & -0.04 & -0.05 \\ -0.12 & -1.60 & 3.64 & -1.59 & -0.04 & -0.07 & -0.08 \\ -0.12 & -0.04 & -1.59 & 3.64 & -1.59 & -0.04 & -0.12 \\ -0.08 & -0.07 & -0.04 & -1.59 & 3.64 & -1.60 & -0.12 \\ -0.05 & -0.04 & -0.07 & -0.04 & -1.60 & 3.63 & -1.67 \\ -0.11 & -0.05 & -0.08 & -0.12 & -0.12 & -1.67 & 2.53 \end{bmatrix}$$



Why sparsity in L^{-1} ?

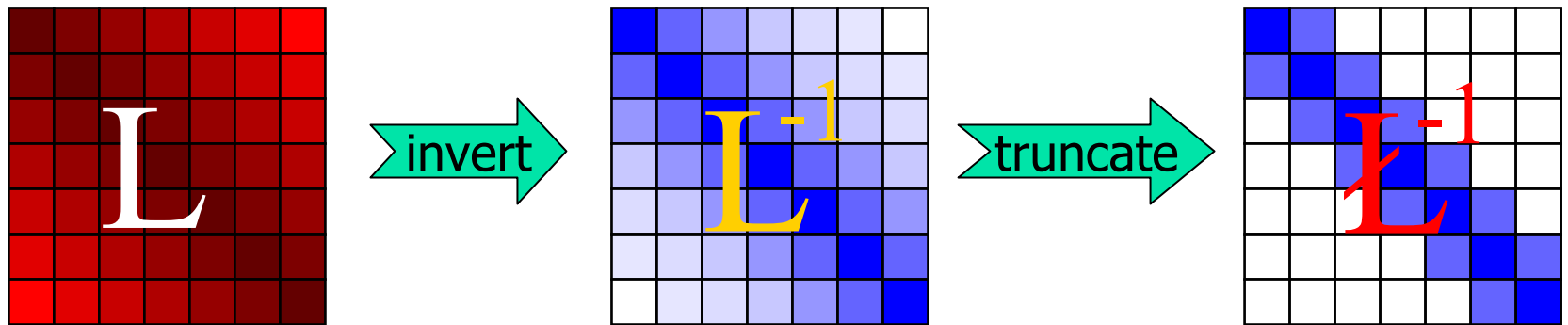


$$M = \frac{\mu}{4\pi A_i A_j} \int_{A_i} \int_{A_j} \int_{L_i} \int_{L_j} \frac{dl_i \cdot dl_j}{R} da_j da_i$$

Similar to scalar potential coefficients encountered in capacitance extraction

$$P_{ij} = \frac{1}{\text{area}(A_i)} \times \int_{x_i \in A_i} \frac{1}{\text{area}(A_j)} \int_{x_j \in A_j} \frac{1}{4\pi\epsilon_0 \|x_i - x_j\|} da_j da_i$$

L^{-1} matrix suggests locality



[A. Devgan et al. (ICCAD 2000)]



Direct Truncation

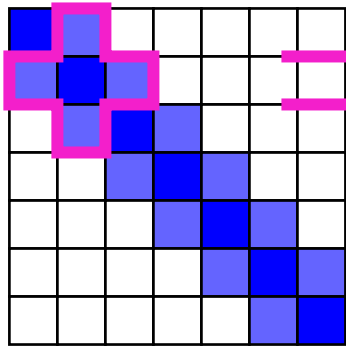
$$L = 10^{-11} \times$$

$$\begin{bmatrix} 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 & 5.13 \\ 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 \\ 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 \\ 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 \\ 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 \\ 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 \\ 5.13 & 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 \end{bmatrix}$$

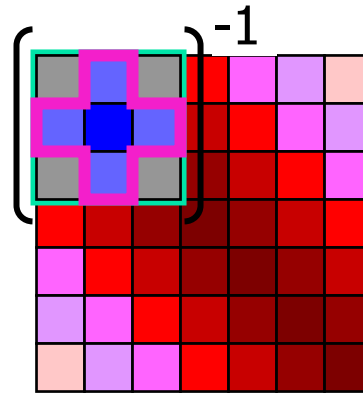
$$L^{-1} = 10^{10} \times$$

$$\begin{bmatrix} 2.53 & -1.67 & 0 & 0 & 0 & 0 & 0 \\ -1.67 & 3.63 & -1.60 & 0 & 0 & 0 & 0 \\ 0 & -1.60 & 3.64 & -1.59 & 0 & 0 & 0 \\ 0 & 0 & -1.59 & 3.64 & -1.59 & 0 & 0 \\ 0 & 0 & 0 & -1.59 & 3.64 & -1.60 & 0 \\ 0 & 0 & 0 & 0 & -1.60 & 3.63 & -1.67 \\ 0 & 0 & 0 & 0 & 0 & -1.67 & 2.53 \end{bmatrix}$$

\mathcal{L} Matrix Contains Redundancy



\mathcal{L}^{-1}



\mathcal{L}

Ł Matrix Contains Redundancy



Numerical Example

$$\begin{bmatrix}
 1 & -0.5 & & & & & & & \\
 -0.5 & 1 & -0.5 & & & & & & \\
 & -0.5 & 1 & -0.5 & & & & & \\
 & & -0.5 & 1 & -0.5 & & & & \\
 & & & -0.5 & 1 & -0.5 & & & \\
 & & & & -0.5 & 1 & -0.5 & & \\
 & & & & & -0.5 & 1 & -0.5 & \\
 & & & & & & -0.5 & 1 & \\
 & & & & & & & -0.5 & 1
 \end{bmatrix}^{-1} = \begin{bmatrix}
 1.75 & 1.50 & 1.25 & 1.00 & 0.75 & 0.50 & 0.25 \\
 1.50 & 3.00 & 2.50 & 2.00 & 1.50 & 1.00 & 0.50 \\
 1.25 & 2.50 & 3.75 & 3.00 & 2.25 & 1.50 & 0.75 \\
 1.00 & 2.00 & 3.00 & 4.00 & 3.00 & 2.00 & 1.00 \\
 0.75 & 1.50 & 2.25 & 3.00 & 3.75 & 2.50 & 1.25 \\
 0.50 & 1.00 & 1.50 & 2.00 & 2.50 & 3.00 & 1.50 \\
 0.25 & 0.50 & 0.75 & 1.00 & 1.25 & 1.50 & 1.75
 \end{bmatrix}$$

$$\begin{bmatrix}
 1.75 & 1.50 \\
 1.50 & 3.00
 \end{bmatrix}^{-1} = \frac{1}{1.75 \cdot 3 - 1.5^2} \begin{bmatrix}
 3.00 & -1.5 \\
 -1.5 & 1.75
 \end{bmatrix} = \begin{bmatrix}
 1 & -0.5 \\
 -0.5 & 0.58
 \end{bmatrix}$$

Numerical Example

$$\begin{bmatrix}
 1 & -0.5 & & & & & \\
 -0.5 & 1 & -0.5 & & & & \\
 & -0.5 & 1 & -0.5 & & & \\
 & & -0.5 & 1 & -0.5 & & \\
 & & & -0.5 & 1 & -0.5 & \\
 & & & & -0.5 & 1 & -0.5 \\
 & & & & & -0.5 & 1
 \end{bmatrix}^{-1} = \begin{bmatrix}
 1.75 & 1.50 & 1.25 & 1.00 & 0.75 & 0.50 & 0.25 \\
 1.50 & 3.00 & 2.50 & 2.00 & 1.50 & 1.00 & 0.50 \\
 1.25 & 2.50 & 3.75 & 3.00 & 2.25 & 1.50 & 0.75 \\
 1.00 & 2.00 & 3.00 & 4.00 & 3.00 & 2.00 & 1.00 \\
 0.75 & 1.50 & 2.25 & 3.00 & 3.75 & 2.50 & 1.25 \\
 0.50 & 1.00 & 1.50 & 2.00 & 2.50 & 3.00 & 1.50 \\
 0.25 & 0.50 & 0.75 & 1.00 & 1.25 & 1.50 & 1.75
 \end{bmatrix}$$

$$\begin{bmatrix}
 3.00 & 2.50 & 2.00 \\
 2.50 & 3.75 & 3.00 \\
 2.00 & 3.00 & 4.00
 \end{bmatrix}^{-1} = \begin{bmatrix}
 0.75 & -0.5 & \\
 -0.5 & 1 & -0.5 \\
 & -0.5 & 0.62
 \end{bmatrix}$$



Windowing Technique

$$L = 10^{-11} \times$$

$$\begin{bmatrix} 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 & 5.13 \\ 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 \\ 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 \\ 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 \\ 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 \\ 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 \\ 5.13 & 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 \end{bmatrix}$$

$$L(1:2, 1:2)^{-1} = 10^{10} \times \begin{bmatrix} \mathbf{2.44} & \mathbf{-1.92} \\ \mathbf{-1.92} & 2.44 \end{bmatrix}$$

$$L(1:3, 1:3)^{-1} = 10^{10} \times \begin{bmatrix} 2.48 & \mathbf{-1.70} & -0.31 \\ \mathbf{-1.70} & \mathbf{3.62} & \mathbf{-1.70} \\ -0.31 & \mathbf{-1.70} & 2.48 \end{bmatrix}$$



Windowing Technique

$$L = 10^{-11} \times$$

$$\begin{bmatrix} 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 & 5.13 \\ 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 & 5.47 \\ 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 & 5.90 \\ 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 & 6.45 \\ 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 & 7.22 \\ 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 & 8.51 \\ 5.13 & 5.47 & 5.90 & 6.45 & 7.22 & 8.51 & 10.80 \end{bmatrix}$$

$$\hat{L}^{-1} = 10^{10} \times$$

$$\begin{bmatrix} 2.44 & -1.70 & 0 & 0 & 0 & 0 & 0 \\ -1.70 & 3.62 & -1.70 & 0 & 0 & 0 & 0 \\ 0 & -1.70 & 3.62 & -1.70 & 0 & 0 & 0 \\ 0 & 0 & -1.70 & 3.62 & -1.70 & 0 & 0 \\ 0 & 0 & 0 & -1.70 & 3.62 & -1.70 & 0 \\ 0 & 0 & 0 & 0 & -1.70 & 3.62 & -1.70 \\ 0 & 0 & 0 & 0 & 0 & -1.70 & 2.44 \end{bmatrix}$$

[T. H. Chen et al. (ICCAD 2002)]